SMD 2835 0.2W Data Sheet



India's first LED Chip – Complying International Quality and Lighting Standards.

Description:

Indo Japan's SMD LED 2835 series products use high quality silica gel packages, which improves the heat dissipation, thus enhancing the performance and reliability of LED Chips.

SMD LED 2835 series has low power consumption, wide beam angle, long product life, which makes this series suitable for all forms of lighting applications.

Features:

- LM80 Compliant
- RoHS & CE Compliant
- Pb free
- Size: 2.8mm x 3.5mm x 0.65mm
- Viewing Angle : 120°
- White LED 2835
- High Lumen Output
- Low Power Consumption

Applications:

- General Lighting
- Automotive Lighting
- Decorative Lighting
- Indicator Lighting
- Switch Lighting

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Absolute Maximum Ratings (Tsoldering / Ta = 25°C)

Parameters	Symbol	Rating	Unit	
Forward Current	I_{f}	90	mA	
Peak Forward Current (Duty 1/10 @10ms)	I_{fp}	110	mA	
Power Dissipation	P_d	297	mW	
Operating Temperature	Topr	-40 ~ +85	°C	
Storage Temperature	T_{stg}	-40 ~ +100	°C	
Thermal Resistance (Junction / Soldering point)	R _{th J-S}	21	°C/W	
Junction Temperature	T _j	125	°C	
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 10 sec.		
		Hand Soldering : 350 °C for 3 sec.		

Note:

1. The products are sensitive to static electricity and must be carefully taken when handling products.

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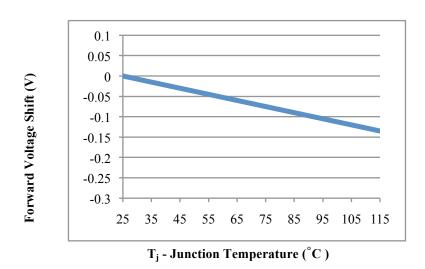
Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Flux	Φ	1500		2000	mcd	$I_f = 65 \text{mA}$
(mcd)						
Wavelength	WLD	520	524	530	nm	$I_f = 65 \text{mA}$
Forward	V_{F}	2.9		3.3	V	$I_f = 65 \text{mA}$
Voltage(2)						
Viewing Angle	201/2		120		deg	$I_f = 65 \text{mA}$
Reverse	I_R			10	μΑ	$V_r = 5V$
Current						

Notes:

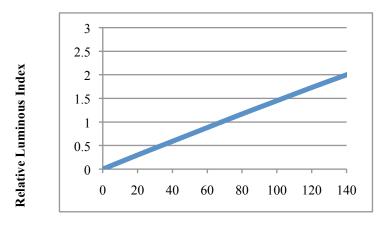
- 1. Tolerance of Luminous flux: ±11%.
- 2. Tolerance of Forward Voltage: ±0.1V.
- 3. Tolerance of Colour Rendering Index: ±2



Relative Luminous Intensity vs Junction Temperature



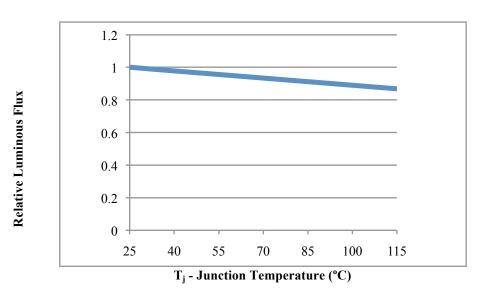
Forward Current vs Relative Luminous Intensity



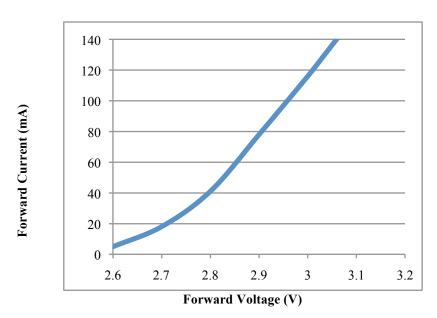
Forward Current (mA)



Relative Luminous Intensity vs Junction Temperature



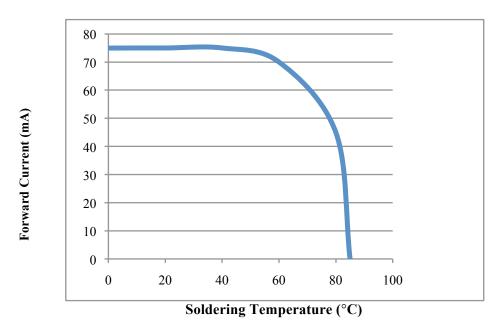
Forward Current vs. Forward Voltage





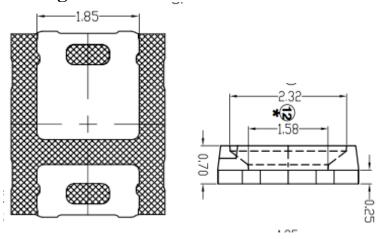
Max Driving Forward Current vs Soldering Temperature

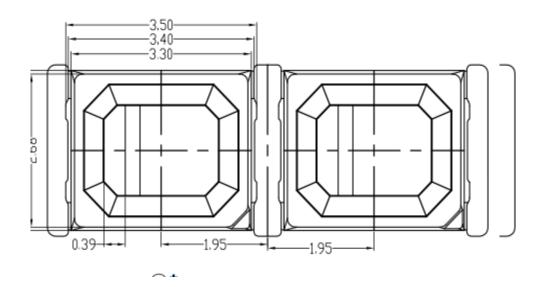
$R_{th\ j\text{-}S=30}\ ^{\circ}C/W$





Package Dimension



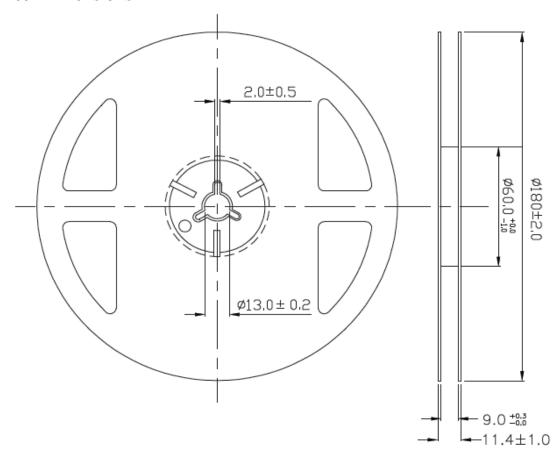


Note:

Tolerance unless mentioned is ± 0.15 mm; Unit = mm



Reel Dimensions

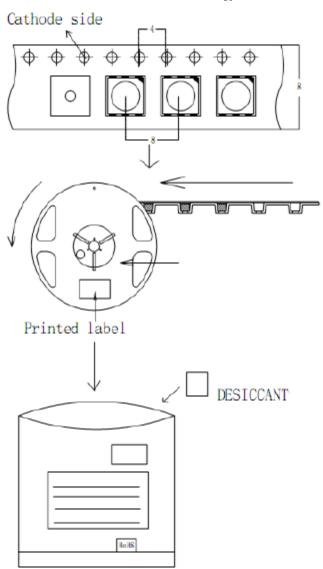


Note:

Tolerances unless mentioned ± 0.1 mm. Unit = mm



Moisture Resistant Packing Process





Notes for Reflow Soldering

- Reflow soldering should not be done more than twice.
- To ensure the reliability, quality and high performance the LED's have been encapsulated with silica gel. It not recommended to put any kind of pressure on the Chip.
- Use of high precision nozzles to avoid any sort of damage to Chips is recommended
- Use of anti-static apparels while operating on LED Chips is recommended
- Ensure high quality earthing/ground wiring.

Notes for Hand Soldering

- Hand Soldering Parameters 300°C for not more than 3 seconds
- Hand Soldering shouldn't be done more than once.
- Avoid using sharp objects for compressing LEDs
- Use of anti-static apparels while operating on LED Chips is recommended

Storage

Before opening vacuum packing

• LEDs can be stored for one year under temperature and humidity not exceeding 30°C and 60% RH.

After opening vacuum packing

• The LED's floor life is 168 Hrs under 30°C or less and 60% RH or less. Unused LEDs should be stored in moisture proof packages.